PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3490505

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
En-Chiuan Liou	08/18/2015
Chih-Wei Yang	08/18/2015
Yu-Cheng Tung	08/18/2015
Chia-Hsun Tseng	08/18/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14830756

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2560USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	08/20/2015

Total Attachments: 8

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PATENT REEL: 036374 FRAME: 0458

503443881



PATENT REEL: 036374 FRAME: 0459

Title of Invention:

SEMICONDUCTIVE DEVICE WITH A SINGLE DIFFUSION BREAK AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or			
☐ United States application nu	_filed on	, or	
☐ PCT international application	n number	filed on	
The above-identified application was	s made or authorized to be made	by me.	
I believe that I am the original invent application.	tor or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	UNITED MICROELECTROI CORP.	NICS having a postal add	dress of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hs	in-Chu City 300, Taiwaı	n, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar		00), the receipt of which is he	ereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w ution and, in and to, all Letters Pat r any continuations, continuation-	which are disclosed in the tent to be obtained for said in-part, divisions, renewals,	
I hereby covenant that no assignment entered into which would conflict with		nce has been or will be made	∍ or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said lecessary or desirable to carry out	Letters Patent and said the proposes thereof.	of signing)
Note: An application data sheet (PTG			

Page 1 of 8

NPO#NAU-P2560-USA:0 CUST#UMCD-2015-0339

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

En-Chiuan Liou

Date:

AUG 1 8 2015

Signature:

En Chivan Lion

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F#NPO-P0002E-US1201 DSC0-104U008275

NPO#NAU-P2560-USA:0 CUST#UMCD-2015-0339

PATENT

Title of Invention:

SEMICONDUCTIVE DEVICE WITH A SINGLE DIFFUSION BREAK AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:	•		
☑ The attached application, or				
☐ United States application nu	mber	file	ed on	, or
☐ PCT international application	number		filed on	
The above-identified application was	made or authorize	d to be made by r	ne.	
I believe that I am the original inventionapplication.	or or an original join	t inventor of a cla	imed invention in	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri	I false statement ma isonment of not mo	ade in this declara re than five (5) ye	ation is punishab ars, or both.	le
In consideration of the payment by	UNITED MICRO CORP.	ELECTRONIC	S having a po	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industri	al Park, Hsin-C	hu City 300,	Taiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of Ond d valuable consider	e Dollar (\$ 1.00), tation.	the receipt of wh	ich is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	nd to any and all imp tion and, in and to, a any continuations.	provements which all Letters Patent i continuation-in-pa	i are disclosed in to be obtained fo art, divisions, ren	n the or said newals
I hereby covenant that no assignmen entered into which would conflict with	it, sale, agreement i this assignment;	or encumbrance h	nas been or will t	e made or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, ir maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said inventi cessary or desirable	on and said Lette to carry out the	rs Patent and sa	aid f. _(Date of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	0/SB/14 or equivale s form. Use this form	nt), including nam n for <u>each additio</u>	ing the entire nal inventor.	

Page 3 of 8

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chih-Wei Yang

Date:

AUG 1 8 2015

Signature:

Page

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P#NPO-P0002E-US1201 DSC0-104U008275

NPO#NAU-P2560-USA:0 CUST#UMCD-2015-0339

PATENT

Title of Invention:

SEMICONDUCTIVE DEVICE WITH A SINGLE DIFFUSION BREAK AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:				
☑ The attached application, or					
☐ United States application number			filed on ,		
☐ PCT international application	number	fi	led on		
The above-identified application was	made or authorized to	be made by me			
I believe that I am the original inventorapplication.	or or an original joint in	ventor of a claim	ed invention in	the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made sonment of not more t	in this declaration han five (5) years	on is punishable s, or both.	Э	
In consideration of the payment by	UNITED MICROEL CORP.	ECTRONICS	having a po	stal address of	
No.3, Li-Hsin Road 2, Science	-Based Industrial I	Park, Hsin-Ch	 u City 300, Т	aiwan, R.O.C.	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	I of the sum of One D d valuable consideration	ollar (\$ 1.00), the on.	e receipt of which	ch is hereby	
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.					
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, in maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	ication, said invention cessary or desirable to	and said Letters carry out the pro	Patent and said poses thereof.	d (Date of signing)	
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.					

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NPO#NAU-P2560-USA:0 CUST#UMCD-2015-0339

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Yu-Cheng Tung

Date:

AUG 1 8 2015

Signature:

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F#NPO-P0002E-US1201 DSC0-104U008275

NPO#NAU-P2560-USA:0 CUST#UMCD-2015-0339

PATENT

Title of Invention:

SEMICONDUCTIVE DEVICE WITH A SINGLE DIFFUSION BREAK AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application number			filed on	
☐ PCT international application	number	f	iled on	
The above-identified application was	made or authorized t	o be made by m	e.	***************************************
I believe that I am the original inventorapplication.	or or an original joint i	nventor of a clair	med invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made sonment of not more	e in this declarat than five (5) yea	ion is punishable rs, or both.	
In consideration of the payment by	UNITED MICROEI CORP.	LECTRONICS	having a postal a	address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Cl	nu City 300, Taiw	an, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	I of the sum of One E d valuable considerati	Dollar (\$ 1.00), th ion.	e receipt of which is	hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	id to any and all impro ion and, in and to, all any continuations, co d as to Letters Patent	ovements which a Letters Patent to ntinuation-in-par any reissue or r	are disclosed in the be obtained for said t, divisions, renewals e-examination thered	d s, of.
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	lication, said invention cessary or desirable to	and said Letters carry out the pr	s Patent and said roposes thereof.	e of signing)
Note: An application data sheet (PTC inventive entity, must accompany this	/SB/14 or equivalent) form. Use this form f	, including namir or <u>each additions</u>	ng the entire al inventor.	

Page 7 of 8

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chia-Hsun Tseng

Date:

AUG 1 8 2015

Signature:

Chia-Usun Isong

Page 8 of 8

F#NPO-P0002E-US1201 DSC0-104U008275

NPO#NAU-P2560-USA:0 CUST#UMCD-2015-0339

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